PRODUCT SPECIFICATION

CS2004C-D-YSXFDYN-100

V1.1

November 9, 2009

Easterntronic LCD Group



REVISION RECORD

REV		D)esci	iption			Page	Date
V1.0	First Relea	ase						Nov 29 ,2006
V1.1	Changed	controller	IC	from	S6A0069X01	to	4,15	Nov 9 ,2009
	ST7066U-	-0A,And add	d qu	ality un	its.			

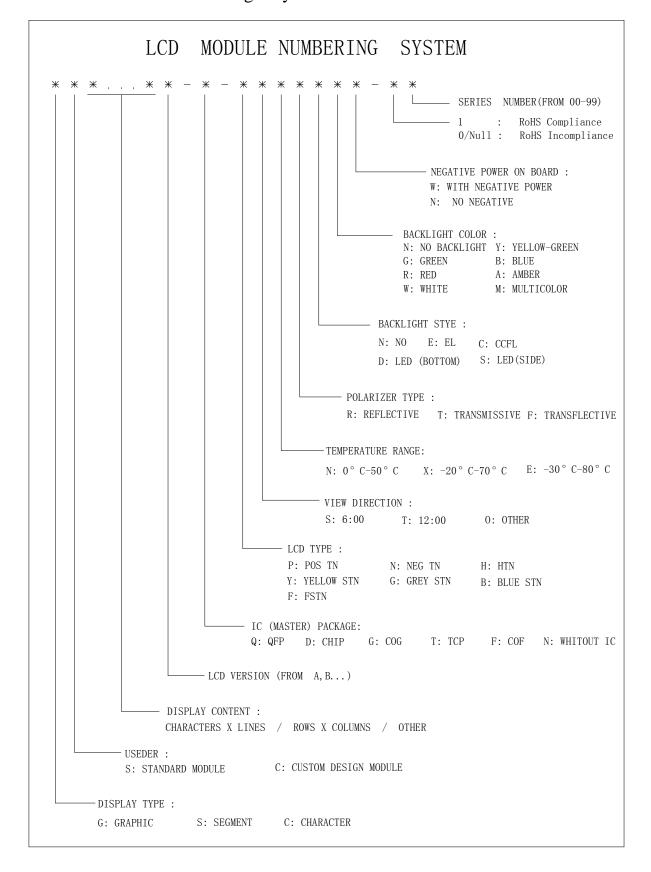


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1. Type Number	And Descri	ption
Type Number	:	CS2004C-D-YSXFDYN-100
Description	:	20Characters X 4Lines
LCD Panel	:	Yellow-green STN, Transflective
Viewing angle	:	6H
Duty	:	1/16
Bias	:	1/5
Operating Ter	nperature:	$-20^{\circ}C - 70^{\circ}C$
Storage Temp	erature :	$-30^{\circ}C - 80^{\circ}C$
Controller	:	ST7066U-OA Or Equivalent
IC package	:	Bonding
BackLight	:	Yellow-green LED, Bottom



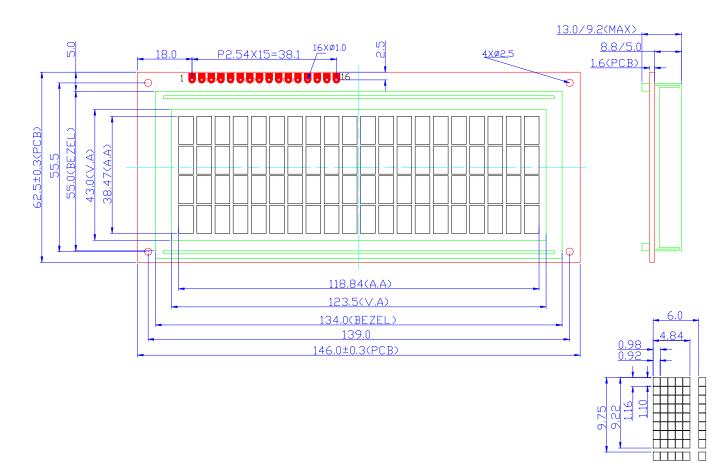






ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	20 CHARACTERS X 4LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	146.0(W) X 62.5(H) X 13.0(T)	mm
EFFECTTVE DISPLAY AREA	123.5(W) X 43.0(H)	mm
CHARACTER SIZE	4.84(W) X 9.22(H)	mm
CHARACTER PITCH	6.0(W) X 9.75(H)	mm
DOT SIZE	0.92(W) X 1.1(H)	mm
DOT PITCH	0.98(W) X 1.16(H)	mm
APPROX WEIGHT	TBD	g
LCD TYPE	Yellow-green STN, TRANSFLEC	TIVE
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	Yellow-green LED, BOTTEM	

3.Mechanical Specifications



* Remark : Non-specific tolerance refers this model. (± 0.2 mm)

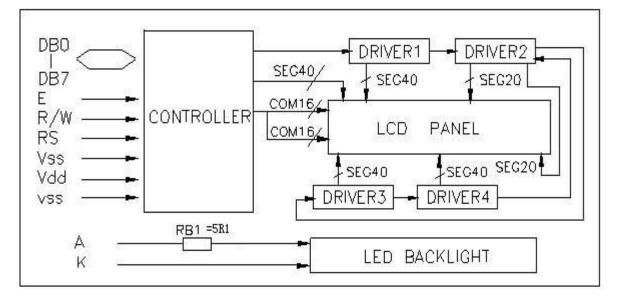
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- 4.Electrical Block Diagram
 - 4.1 Pin Definition

PIN	SYMBOL	FUNCTION					
1	Vss	Power Supply(0V,GND)					
2	Vdd	Power Supply For Logic					
3	Vo	Contrast Adjust					
4	RS	Instruction/Data Register Select					
5	R/W	Data Read/Write					
6	Е	Enable Signal					
7-14	DB0-DB7	Data Bus Line					
15	А	Power Supply For LED B/L(+)					
16	K	Power Supply For LED B/L(-)					

4.2 Electrical Block Diagram



4.3 Display Character Address Code

DISPLAY POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM	00	01	02	03	04	05	06	07	08	09	ОA	0B	0C	0D	0E	0F	10	11	12	13
BBHWWH	40	41	. —	• =					• =				• =	4D	. —					
ADDRESS	14		16																	
	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

5. Absolute Maximum Ratings

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	_	-0.3	Vdd +0.3	V

5.1 Electrical Maximum Ratings(Ta=25deg C)

5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

6.ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%

ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.5	4.7	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA
Supply Voltage (LED)	V-bl	see note 1	3.9	4.2	4.4	V
*Supply Current (B/L)	lf	see note 1	-	200	540	mA
*Peak forward current(B/L)	lfp	I mseo pulse 10% Duty Cycle	-	-	1944	mA
*Power dissipation(B/L)	Pd		-	-	2376	mW

Note 1: LED backlight chips are arranged in two branches of 2 in series

*For operation above 25° C, the If, Ifp&Pd must be derated, the current derating is -10.8 mA/°C for DC drive and -11.13 mA/°C for pulse drive, the power dissipation is -45.36 mW /°C. The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.

6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V

6.2.1 Write mode

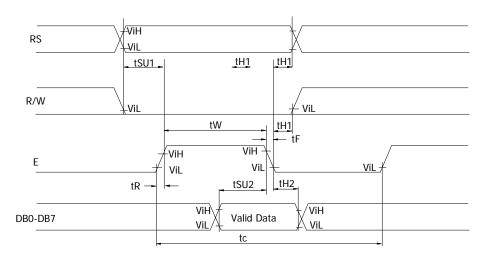
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

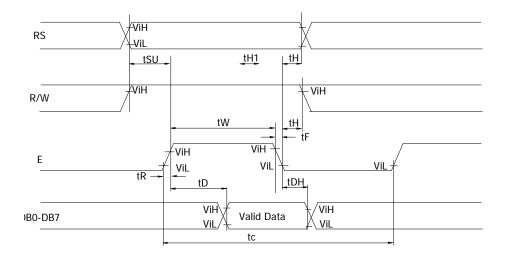
6.2.2 Read mode

ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

6.2.3 Timing Diagram

WRITE MODE TIMING DIAGRAM

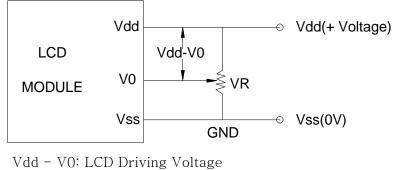




READ MODE TIMING DIAGRAM

7. EXAMPLE OF POWER SUPPLY

It is recommended to apply a potentiometer for the contrast adjust due to the tolerance of driving voltage and its temperature dependence.



VR: 10K - 20K

8. Electro-Optical Characteristic

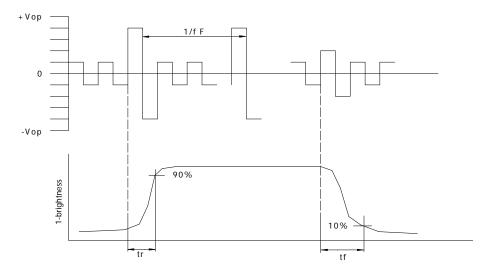
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.	
Contrast	CR	25 ℃		12			Note1	
Rise Time	tr	25 ℃		160	240	ms	Note2	
Fall Time	tf	25 ℃		100	150	ms	note 2	
Viewing Angle	θ 1- θ 2	25 ℃			60	DEG	Noto 2	
Viewing Angle	Ø1, Ø2	250	-40		40	DEG	Note 3	
Frame Frequency	Ff	25 ℃		70		Hz	note 2	



Note(1): Contrast ratio is defined under the following condition:

- brightness of non-selected condition CR= brightness of selected condition
- Temperature-----25C (a).
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- $\theta = 0, \emptyset = 0$
- (d). Operating Voltage---4.7V

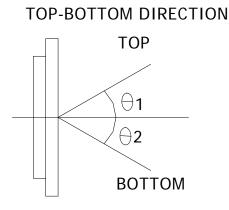
Note(2): definition of response time:



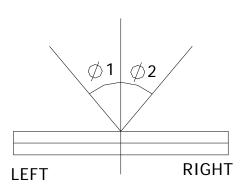
Condition:

- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- Viewing angle----- $\theta = 0, \ \emptyset = 0$ (c).
- **Operating Voltage---4.7V** (d).

Note(3): definition of view angle:



RIGHT-LEFT DIRECTION

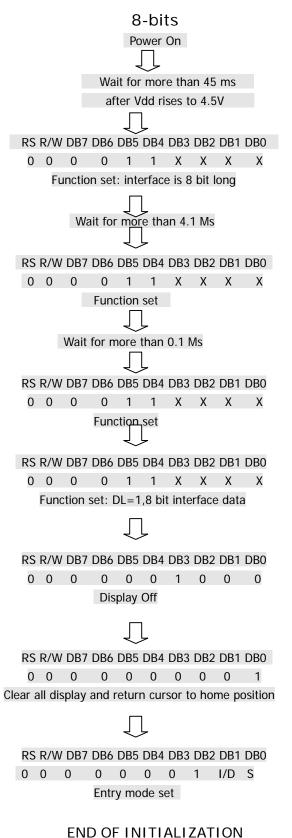




9.Instruction Table

Function	D	D									Description	Execu		
TUNCTION			В								•	Time*		
		vv					3							
Clear	0	0			_		_		_			(Max)		
Clear	ľ	0	0	0	0	U	U	U	0		Clears entire display and returns the cursor to	1.64m5		
Display		_	_	_	_	•	_	•		_	home position (address 0)	1 (1 - 0		
Return	0	0	0	0	0	0	0	0	1	Х	Return the cursor to the home position. DD RAM			
Home											ontents remain unchanged. Set DD RAM address			
											to zero.			
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 µ S		
mode									/		shift of the display. These operations are			
set									D		performed during data write/read of DD RAM/CG			
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:			
											whole display shift when data is written.			
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 µ S		
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.			
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;			
											B=0, Blink OFF.			
Cursor or	0	0	0	0	0	1	S	R	Х	Х	Move the cursor and shift the display without	40 µ S		
Display							/	1			changing DDRAM contents. S/C=1: Display Shift;			
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;			
											R/L=0:shift to left.			
Function	0	0	0	0	1	D	Ν	F	Х	Х	Set interface data length (DL), number of display	40 µ S		
Set						L					lines (N) and character font (F).DL=1: 8 bits;			
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. F=1:			
											5X11 dots; F=0: 5X7 dots.			
Set CG	0	0	0	1			AC	CG	i i		Set CG RAM address. CG RAM data is sent and	40 µ S		
RAM add											received after this setting.			
Set DD	0	0	1			Α	D	D			Set DD RAM address. DD RAM data is sent and	40 µ S		
RAM Add											received after this setting.			
Read BF	0	1	В				AC	;			Read BUSY FLAG (BF) and the contents of the	0 µ S		
& Addr	ľ		F			-					address counter. BF=1: internal operation; BF=0:			
			ľ								can accept instruction.			
Write Data	1	0	1	۱. ۱/۱	<u> </u>	TF	: г	۵(ΤĮ	7	Write data into DD RAM or CG RAM.	40		
to RAM	['	ľ	`	v V I			- L			•		μS**		
Read Data	1	0	$\left \right $	DI	- ^	D	D	۸-	Г٨		Read data from DD RAM or CG RAM.	μ 40		
from RAM	'	0		КI	LH	U	ט	А	iA			40 μ S**		
												μJ		

10.Initialization By Instruction



4-bits Power On Wait for more than 45 mS after Vdd rises to 4.5V RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 Function set: DL=1,8 bit interface data. Wait for more than 4.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 DL=1,8 bit interface data Wait for more than 0.1 Ms RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 0 0 N F X X Function set: DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 1 0 0 0 Display Off ٦Ļ RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 0 1 Function set: DL=0.4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 1 I/D S Entry mode set END OF INITIALIZATION



11.Software Examples

8-BIT OPERATION 8 characters X 2 lines

Function	RS R	W D7	' D6	D5	D4	D3	D2	D1	D0	DISPLAY	DESCRIPTION
Power on delay				-	-	-			-		Initialization. No display appears.
Function set	0 0	0	0	1	1	0	0	Х	Х		Sets 8-bit operation, 2-line display and 5*7
											dots character font.
Display OFF	0 0	0	0	0	0	1	0	0	0		Turn off display.
Display ON	0 0	0	0	0	0	1	1	1	0		Turn on display and cursor.
Entry Mode set	0 0	0	0	0	0	0	1	1	0		Set mode to increment the address by one
											and to shift the cursor to the right, at the
											time of write to the DD/CG RAM. Display
											is not shifted.
Write data to	1 0	0	1	0	0	1	1	1	1	0	Write "O". Cursor incremented by one and
CG/DD RAM											shift to right.
Write data to	1 0	0	1	0	1	0	0	1	0	OR	Write "R". Cursor incremented by one and
CG/DD RAM											shift to right
Write data to						•				ORIENT	Write "I" "E" "N" "T".
CG/DD RAM											
Set DDRAM	0 0	1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the cursor is
address											positioned at the head of the Second line
Write data to						•				ORIENT	Write "D" "S".
CG/DD RAM										DS	
Cursor or display	0 0	0	0	0	1	0	0	Х	Х	ORIENT	Shift only the cursor position to the left.
shift										DS	
Write data to				•						ORIENT	Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM										DISPLAY	

4-bit operation (4-bits 1 line)

Function	RS	RW	' D7	D6	D5	D4	Display	Description	
power on delay								Initialization. No display appears.	
Frnction set	0	0	0	0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8-bits by initialization, and Only this instruction completes with one write.	
Frnction set	0 0	0 0	0 0	0 0	1 X	-		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be changed hence after.)	
Display ON/OFF Control		0 0	0 1	0 1	0 1		_	Turn on display and cursor.	
Entry Mode Set		0 0	0 0	0 1	0 1		_	Turn on display and cursor.	
Write data to CG/DD/ARM		0 0	0 1	1 1	0 1	0 1		Write "O". Curaor incrementer by one and shift to right.	
	same as 8-bit operation								

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

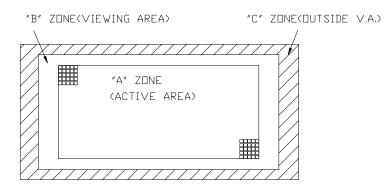
12.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): $1 \sim 6 \text{ pcs LCD}$ screens are cut out of from each $14" \times 16"$ mother glass. Middle size(M): $7 \sim 50$ pcs LCD screens are cut out of from each $14" \times 16"$ mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each $14"\times16"$ mother glass.

12.4 Quality Specification

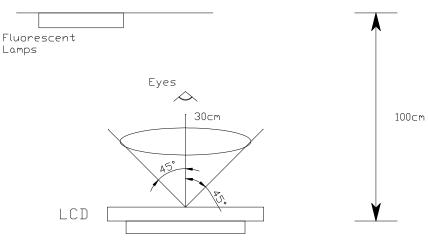
12.4.1 Conditions of Cosmetic Inspection

12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: $65 \pm 20\%$ RH Ambient Luminance: 40-watt fluorescent lamp. An appearance test should be conducted by human sight at approximately 30 cm distance



from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument

- LCD module tester



- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of defects	Inspectio	on criterion	Drawing specification
Major	1.Non-display	Product no function	Not	accept	
defect	2.LCD with wrong view direction`	Difference in Spec.	Not accept		
	3.Segment missing	Part or all pattern do not light up	Not accept		
	4.Occur high current	Current exceed designed value	Not	accept	
	5. LC leakage	LC does not fulfill the glass cell	Not	accept	
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	-	to dimensions e specification	
	7.Wrong type applied	Wrong polarizer attachment Pin attached wrong	Not accept Not accept		
	8.Incorrect pins quality	type applied Pin attached wrong quantity applied	Not	accept	
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1 0.10 <a≤0.15< td=""><td>Acceptab numbe Not count (Should not be connected to nex dot) 1 pc / dot(on segment)or less 2 pcs / cell or less (Should not be connected to nex dot)</td><td>$\frac{er}{dt}$</td></a≤0.15<>	Acceptab numbe Not count (Should not be connected to nex dot) 1 pc / dot(on segment)or less 2 pcs / cell or less (Should not be connected to nex dot)	$\frac{er}{dt}$



			$B \le 0.10$	Not count	
Minor defect	10.Pinholes	Black spot/white spot at activated state	1m distance enlarge unde 2. Middle si Diameter(mm $\Phi \le 0.15$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.35$ $\Phi > 0.35$ 3. Small size Diameter(mm $\Phi \le 0.15$ $0.15 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $\Phi > 0.30$ 4. For the accept if defect is equal to lattice's 5. Only allo one segm 6. The nea allowed pinholes i Remarks : product in (including TN, with normal dr white dot size equal 0.2mm(driving voltage than the normal be abnormal voltage	n't be found at e and will not r electronic test ze LCD n) Accept QTY Not count 3 1 0 e LCD n) Accept QTY Not count 2 1 0 dot pattern: f the area of less than or half of one w one defect in ent arest diatance between two is 20mm Regarding the negative type STN and FSTN), iving voltage, the should be less or $\Phi \le 0.2$). If the e is lower 0.3V I voltage, it can not ite dot base on ge.	$\Phi = (X+Y)/2$
	s and foreign matters	Black spot/dust on LCD(non-display)			► ► ► ►

under electronic test:	$\Phi = (X+Y)/2$
-Middle size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 3	
$0.25 < \Phi \le 0.35$ 1	
$\Phi \! > \! 0.35$ 0	
-Small size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 2	
$0.25 < \Phi \le 0.30$ 1	
$\Phi \! > \! 0.30$ 0	
2.B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
Notcount.	
Negative panel:	
1. A zone	
-Large size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.30$ 4	
$0.30 < \Phi \le 0.50$ 1	
$\Phi\!>\!0.50$ 0	
-Middle&small size LCD	
Diameter(mm) Accept QTY	
$\Phi \leq$ 0.15 Not count	
$0.15 < \Phi \le 0.25$ 3	
$\Phi\!>\!0.25$ 0	
2. B zone	
1.5 times of acceptable	
largest diameter size of Zone	
Α	
3.C zone	
No count	
The nearest diatance allowed	
between two black spot is	
20mm	

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	
scratches	surface.And		
scratches		- Large size LCD	
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 3 = 0$	
		W>0.05 As the spot criteria.	
		I.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$ 1	
		$0.02 < W \le 0.03, L > 4 = 0$	
		$0.03 < W \le 0.05, L > 2$ 0	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03$,L > 5 0	
		$0.03 < W \le 0.05, L > 4 0$	
		W>0.05 As the spot criteria.	
		1	
		-Middle size LCD	
I	1		

			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. -Small size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. 2. B zone 1.5 times of acceptable largest diameter size of Zone A 3.C zone Not count The nearest diatance allowed between two defects is 20mm	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	distance. According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	



		ſ					
Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink	Accept i	f the thick			
		pattern/line	less than	n equal to	25% s	segment	
		jagged		r accordi			
		5 66	specimer		C		
		17.3 Light		activated	with	current	
		leakage		ht appears			
		iounugo		ble or scra			
			-	misalign			
			to the ph	nhole spec	meano		
		17.4 Ink printing	Reject if	the thick	or thin	in more	
		pattern/line	than $1/2^{V}$		or unin	III IIIOIC	
		uneven		hen W1-V	W2~1/3V	X/	
		uneven	Reject w		V 2 \le 1/ 3		
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	σ	defect:	`
defect	10. I in delect	or foreign		,damage(i	0		
uereet		material on		damaged)			
		terminal legs		om glass			
		terminar legs		-	5 01 1	erminai	
		18.2 Pin	legs.Not		nacifico	tion	
			Accoluii	ng to the s	pecifica	luon	
		deviation over					
		tolerance			1	I	
Mintor	19. Chipped	19.1 Chip in	а	b	с	accept	
defect	glass on	lead contact				QTY	
	comer	area.	a≤5mm	b≤W	c≤T		
			L>5m			3	ITO
			m				
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			L<5m				b c à
			m				
		19.2 Others		ceed $1/2$			
			width of	seal	c≤T	3	
		1	1		1	1	1



Mintor defect	20. Glass	a	b	с	accept QTY	A A A A A A A A A A A A A A A A A A A		
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	C C	
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	с	accept QTY	ITD	
defect			a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3		
		21.2 Glass chip on ITO back	a	b	с	accept QTY		
			a≤5mm	b≤W/3	c≤T	3		
Mintor defect	22. Mechanical	Extended crack inspector shall	b		accept	QTY		
	damage	attempt to remove the chip with tweezers,re-eval	b≤W/4		2			
		uate if the remaining defect is still a crack or a chip						
Mintor defect	23.Gla	ass cracks	Not acce	pt				
defect Q	nimum space be TY in total:	etween any 2 defec ≤ 5/unit, Zone B≤ 5		rt) should	l more	than 20m	m, and max. allowed	

Middle size LCD: Zone A \leq 3/unit, Zone B \leq 3/unit;

Small size LCD: Zone A \leq 2/unit, Zone B \leq 2/unit;



12.4.5.2 Other part

NO.	Items	Criterion of defects	AQL
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight. 	
		3. Not allow unlighted on backlight.	Major
		4. Colour and luminance of backlight should correspond its specification.	Major
2	PCB,COB	1.COB seal may not have pinholes larger than0.2mm or contamination.	
		2.COB seal surface may not have pinholes through to the IC.	Minor
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor
	5.No oxidation or contamination on PCB connector.		Minor
		6.Parts on PCB should correspond the characteristic, and not	Major
		allow wrong parts, missing parts or additional parts.	
		7.The jumper on the PCB should correspond to the characteristic.	Minor
		8.The solder which gets on bezel,LED pad,zebra pad or screw hole pad should be smoothed down.	Major
		1. No unmelted solder pastes on the PCB.	Minor
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor
		3. No short circuits in components on PCB.	Minor
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor
		2. No solder residue or solder balls on product.	Minor
		3. The IC on TCP may not be damaged.	Major
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor
		5. Packing method correspond the specification.	Major
		6. Dimension and structure correspond the specification sheet.	Major
		7. No dirt and break on the heat seal.	Major



12.5 Reliability

Item	Condition	ondition				
High temperature operation	$+70^{\circ}\text{C}\pm2^{\circ}\text{C}$, 8 hours					
Low temperature operation	$-20^{\circ}\text{C}\pm 2^{\circ}\text{C}$, 8 ho	1.Total current consumption				
Humidity	Operation	40° C $\pm 2^{\circ}$ C ,93% ± 2 % RH,8 hours	should be below double of initial			
	Storage	40 °C ± 2 °C ,93% ± 2%RH, 24 hours	value. 2.Cosmetic defects			
High temperature storage	$+80^{\circ}\text{C}\pm2^{\circ}\text{C}$, 10 hours		should not be happened			
Low temperature storage	$-30^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 10 h					
Thermal shock	-20°C∼ +70°C					
storage	60min~60min, 5 cy					
Vibration test	Amplitude:0.7~1.0 in each direction(X					
Shock test	To be measured after dropping from 60cm or					
	80cm high on the c					
	state.(weight≥15k					
	Weight <15Kg,dro					
	G B	Dropping method corner dropping A corner: once Edge dropping B,C,D edge: once B0cm ELF,G face: once				
Remark: The function test shall be conducted after 4 hours storage at the normal						
temperature and humidity after removed from the test chamber.						

The LCD module shall not fail the following reliability test.

13. Precaution For Using LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

Wipe off saliva or water drops immediately. (3). Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.

(5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280 $^\circ\!\mathrm{C}\pm10^\circ\!\mathrm{C}$

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

Response time increases with decrease in (3). temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

14. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2004C-D-YSXFDYN-100 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

•Lead

• Mercury

● Cadmium

•Hexavalant chromium

Polybrominated biphenyls

• Polybrominated diphenylethers

And to the annex which points out the exempted implementations \Box To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• 0ils containing polychlorinated biphenyl

Asbestos

• Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on November 9, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for 2009 mium.